

Electronic Patent Application Fee Transmittal

Application Number:	10730834			
Filing Date:	08-Dec-2003			
Title of Invention:	Chip structure with bumps and testing pads			
First Named Inventor/Applicant Name:	Nick Kuo			
Filer:	Winston Hsu			
Attorney Docket Number:	JCLA11759			
Filed as Small Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	2251	1	60	60

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				60